

Title (en)
METHOD FOR ESTABLISHING AN ELECTRICAL AND MECHANICAL CONNECTION BETWEEN CHIP CONTACT SURFACES AND ANTENNA CONTACT SURFACES AND TRANSPONDER

Title (de)
VERFAHREN ZUM ELEKTRISCHEN UND MECHANISCHEN VERBINDEN VON CHIPANSCHLUSSFLÄCHEN MIT ANTENNENANSCHLUSSFLÄCHEN UND TRANSPONDER

Title (fr)
PROCEDE POUR ETABLIR UNE LIAISON ELECTRIQUE ET MECANIQUE ENTRE DES PASTILLES DE PUCE ET DES PASTILLES D'ANTENNE ET TRANSPONDEUR

Publication
EP 1856729 A1 20071121 (DE)

Application
EP 06724965 A 20060308

Priority
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Abstract (en)
[origin: DE102005016930A1] The method involves hooking contact surfaces (11, 12) of a chip, having a set of wire-shaped hooks/lugs (13) on their surfaces, with contact surfaces (19, 20) of a strip substrate, having a set of hooks/ lugs (16) on their surfaces, by applying pressure on the surfaces (19, 20). An RFID antenna is arranged on the substrate. Electrically conducting wires are used as a material for the hooks/lugs with a size in a nanometer range.

IPC 8 full level
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H01L 23/49811 (2013.01 - EP US); **H01L 23/49855** (2013.01 - EP US); **H01L 24/05** (2013.01 - EP US); **H01L 24/13** (2013.01 - EP US); **H01L 24/72** (2013.01 - EP US); **H01L 24/81** (2013.01 - EP US); **H05K 3/325** (2013.01 - EP US); **H01L 2224/0401** (2013.01 - EP US); **H01L 2224/05599** (2013.01 - EP US); **H01L 2224/81345** (2013.01 - EP US); **H01L 2224/81385** (2013.01 - EP US); **H01L 2224/81897** (2013.01 - EP US); **H01L 2224/83897** (2013.01 - EP US); **H01L 2224/85399** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/014** (2013.01 - EP US); **H01R 4/26** (2013.01 - EP US); **H05K 2201/10674** (2013.01 - EP US); **H05K 2201/209** (2013.01 - EP US)

Citation (search report)
See references of WO 2006094989A1

Citation (examination)
US 2003136503 A1 20030724 - GREEN ALAN [US], et al

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